

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	38364	wafer same (cooling or heating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 09:21
L2	1515	1 and fluid and (heat adj transfer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 09:23
L3	199	2 and (support same height)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 09:26
L4	1103	1 and (support same height)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 09:24
L5	159	3 and var\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 09:25
L6	25	2 and (support same height same var\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 10:12
L7	98	1 and (support same height same var\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 12:27
L8	378	1 and (guide with pins)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 14:33

L9	4	kim-choung-hyep.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 14:34
L10	0	jang-sung-ii.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 14:34
L11	58	jang-sung-\$.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 14:34
L12	3	park-kyung-seo.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 14:35
L13	2	chyun-ki-hyon.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 14:35
L14	18	chae-hee-sun.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/19 14:35
S1	1	"165"/\$.ccls. and thermal adj processor and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/09/10 10:58
S2	380	"165"/\$.ccls. and wafer and cooling	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/09/10 10:58
S3	441	"165"/\$.ccls. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/09/10 10:59

S4	238	("165"/\$.ccls. and wafer) and heating and cooling	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/09/10 11:00
S5	73	((("165"/\$.ccls. and wafer) and heating and cooling) and gas and coolant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/09/10 11:01
S6	1	("5846376").PN.	USPAT; USOCR	OR	OFF	2003/09/11 09:24
S7	292	(165/263).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/09/11 09:55
S8	470	(165/80.2).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/09/11 10:04
S9	863	(165/80.4).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/09/11 11:42
S10	326	(165/80.5).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/09/11 11:47
S11	1705	(118/724).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/09/11 12:32
S12	2329	(118/728).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/09/11 12:33
S13	1	("5346578").PN.	USPAT; USOCR	OR	OFF	2004/05/12 12:59
S14	1	("5810933").PN.	USPAT; USOCR	OR	OFF	2004/05/12 12:59

S15	16	"5810933".URPN.	USPAT	OR	OFF	2004/05/12 12:59
S16	1	("5810933").PN.	USPAT; USOCR	OR	OFF	2004/05/13 10:24
S17	0	Mitrovic-Andre-S.IN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/05/13 10:01
S18	16	Mitrovic-Andrej-S.IN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/05/13 10:04
S19	0	Gilbert-lianjun-liu.IN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/05/13 10:05
S20	16	"5810933".URPN.	USPAT	OR	OFF	2004/05/13 10:39
S21	35	("4184188" "4384918" "4502094" "4508161" "4680061" "4743570" "4771730" "4909314" "5155652" "5160152" "5203958" "5213349" "5223113" "5255153" "5267607" "5320982" "5345999" "5346578" "5366002" "5382311" "5460684" "5474614" "5478429" "5484011" "5517753" "5528451" "5530616" "5531835" "5539179" "5542559" "5572398" "5581874" "5583736" "5665166" "5675471").PN.	USPAT	OR	OFF	2004/05/13 10:12
S22	0	("mountsier-thomas.in.").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/05/13 10:30
S23	0	("Mountsier-Thomas-.IN.").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/05/13 10:31
S24	2	Mountsier-Thomas.IN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/05/13 10:32
S25	4	WING-JAMES.IN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/05/13 10:35
S26	2	((("5382311") or ("0644577")).PN.	USPAT; USOCR; EPO	OR	OFF	2004/05/13 10:37

S27	0	("0644577").PN.	USOCR; EPO; DERWENT	OR	OFF	2004/05/13 10:37
S28	1	"5810933".PN. and temperature WITH difference	USPAT	OR	ON	2004/05/13 10:41
S29	1	"5810933".PN. and temperature WITH difference and percent	USPAT	OR	ON	2004/05/13 10:48
S30	97	"165"/\$.ccls. and wafer and chuck	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2004/05/13 11:13
S31	16	("165"/\$.ccls. and wafer and chuck) and rough\$	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2004/05/13 10:49
S32	1987	"118"/\$.ccls. and wafer and chuck	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2004/05/13 11:13
S33	284	("118"/\$.ccls. and wafer and chuck) and rough\$	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2004/05/13 11:13
S34	0	("165"/\$ or "156"/\$ or "118"/\$ or "204"/\$ or "361"/\$).ccls. and wafer and chuck and ((roughness WITH surface) WITH ("m.u.m"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 06:12
S35	0	("165"/\$ or "156"/\$ or "118"/\$ or "204"/\$ or "361"/\$).ccls. and wafer and chuck and ((roughness WITH surface) same ("m.u.m"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 06:10
S36	0	("165"/\$ or "156"/\$ or "118"/\$ or "204"/\$ or "361"/\$).ccls. and chuck and ((roughness WITH surface) same ("m.u.m"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 06:11
S37	403	("165"/\$ or "156"/\$ or "118"/\$ or "204"/\$ or "361"/\$).ccls. and chuck and (roughness WITH surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 06:11

S38	0	S37 and "m.u.m"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 06:12
S39	217	S37 and "mu.m"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 06:12
S40	90	("165"/\$ or "156"/\$ or "118"/\$ or "204"/\$ or "361"/\$).ccls. and wafer and chuck and ((roughness WITH surface) WITH ("mu.m"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 06:32
S41	2	("165"/\$ or "156"/\$ or "118"/\$ or "204"/\$ or "361"/\$).ccls. and wafer and chuck and ((roughness WITH surface) WITH (percent))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 09:09
S42	1	("5864176").PN.	USPAT	OR	OFF	2004/12/27 09:09